

ABSTRACT

A dicing/die bonding adhesion tape includes a
5 substrate, a silicone adhesive layer, and a bonding layer. A
tack strength of 0.2-2.0 N/25 mm is developed between the
silicone adhesive layer and the bonding layer. The bonding
layer is formed of a bonding composition comprising (A) a
polyimide resin, (B) an epoxy resin, and (C) an epoxy resin
10 curing catalyst.